

FLY-801 TO

Laser Diode Wire bonder

Product descriptions and features

Features

- Thermosonic high speed bonding, fast conversion
- Vision system: Programmable look ahead PR
- Multiple die and level bonding capability
- Rotating platform
- Bonding on crossed planes at any angle

Wire Type

Au

Applied Range

Optical communications



KEJIE website

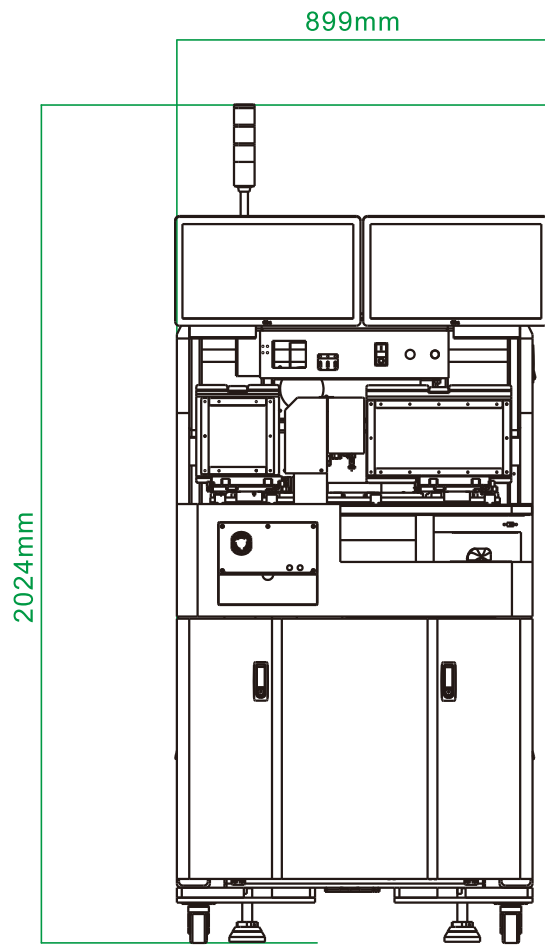


KEJIE wechat

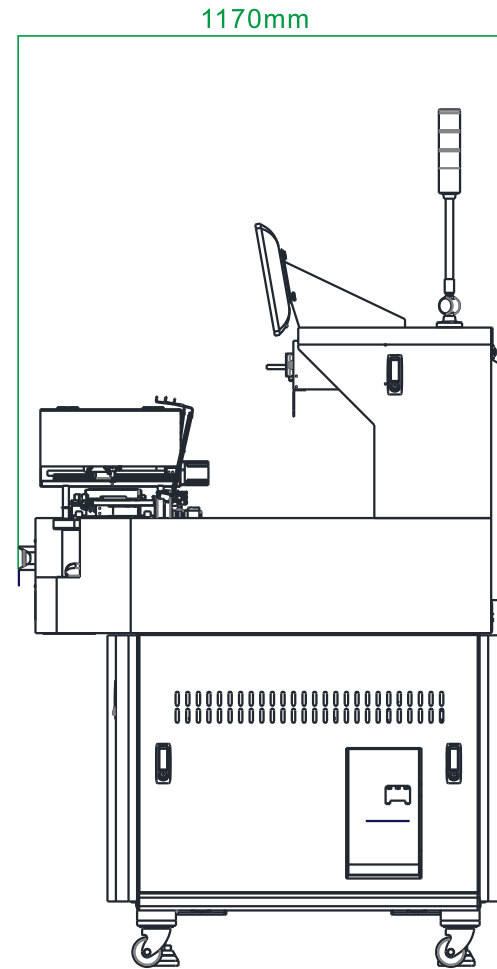
Parameters

Item	Parameter
Bonding Technology	Thermosonic bonding
Optics	Single path or double paths (optional)
Bonding Accuracy	±3.0μm
Bonding area	56x70mm
Cycle time	Parallel planes: 60ms/wire Crossed planes: 80ms/wire
Wire diameter	17μm-50μm

Machine dimension



Front



Left